



芯基科技

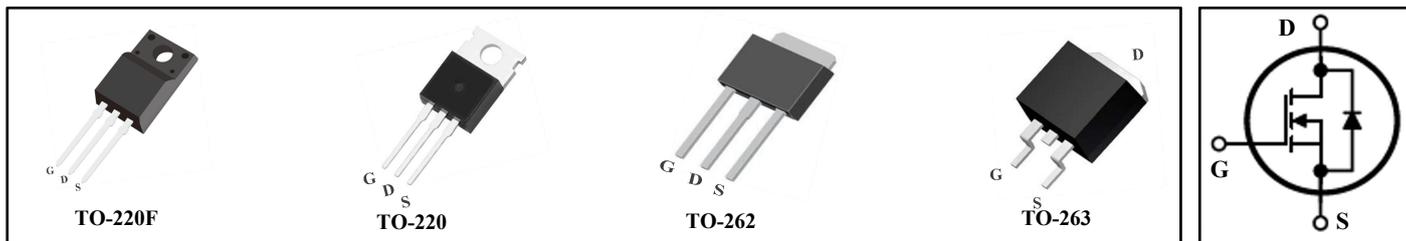
# MPVX10N65B Series Power MOSFET

## FEATURES

- $BV_{DSS}$ : 650V,  $I_D=10A$
- $R_{DS(on)}$  : 1.1 $\Omega$ (Max) @ $V_{GS}=10V$
- Very Low FOM ( $R_{DS(on)} * Q_g$ )
- Excellent stability and uniformity

## APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- AC to DC Converters



## Ordering Information

Type NO.	Marking	Package Code
MPVA10N65B	MPVA10N65B	TO-220F
MPVP10N65B	MPVP10N65B	TO-220
MPVH10N65B	MPVH10N65B	TO-262
MPVC10N65B	MPVC10N65B	TO-263

## Absolute Maximum Ratings $T_C = 25^\circ C$ , unless otherwise noted

Parameter	Symbol	Value		Unit
		220F	220-262-263	
Drain-Source Voltage ( $V_{GS} = 0V$ )	$V_{DSS}$	650		V
Continuous Drain Current	$I_D$	10		A
Pulsed Drain Current (note1)	$I_{DM}$	40		A
Gate-Source Voltage	$V_{GSS}$	$\pm 30$		V
Single Pulse Avalanche Energy (note2)	$E_{AS}$	720		mJ
Avalanche Current (note1)	$I_{AR}$	8		A
Repetitive Avalanche Energy (note1)	$E_{AR}$	45		mJ
Power Dissipation ( $T_C = 25^\circ C$ )	$P_D$	65	147	W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55~+150		$^\circ C$

## Thermal Resistance

Parameter	Symbol	Value		Unit
		220F	220-262-263	
Thermal Resistance, Junction-to-Case	$R_{thJC}$	1.92	0.85	$^\circ C/W$
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	62.5	60.0	



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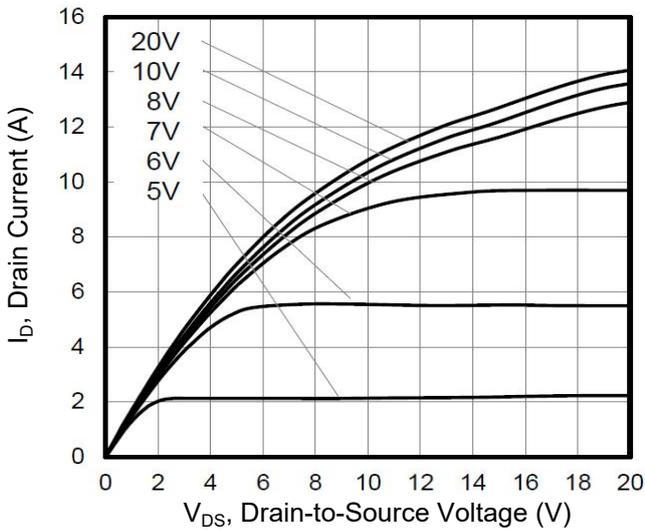
Specifications $T_J = 25^\circ\text{C}$ , unless otherwise noted						
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	650	--	--	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 650V, V_{GS} = 0V, T_J = 25^\circ\text{C}$	--	--	1	$\mu\text{A}$
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 30V$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.0	--	4.0	V
Drain-Source On-Resistance (Note4)	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 5A$	--	0.85	1.1	$\Omega$
<b>Dynamic</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0V,$ $V_{DS} = 25V,$ $f = 1.0\text{MHz}$	--	1573	--	pF
Output Capacitance	$C_{oss}$		--	138	--	
Reverse Transfer Capacitance	$C_{rss}$		--	15	--	
Total Gate Charge	$Q_g$	$V_{DD} = 520V, I_D = 10A,$ $V_{GS} = 10V$	--	33	--	nC
Gate-Source Charge	$Q_{gs}$		--	7	--	
Gate-Drain Charge	$Q_{gd}$		--	13	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 325V, I_D = 10A,$ $R_G = 25\Omega$	--	23	--	ns
Turn-on Rise Time	$t_r$		--	15	--	
Turn-off Delay Time	$t_{d(off)}$		--	90	--	
Turn-off Fall Time	$t_f$		--	30	--	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Body Diode Current	$I_S$	$T_C = 25^\circ\text{C}$	--	--	10	A
Pulsed Diode Forward Current	$I_{SM}$		--	--	40	
Body Diode Voltage	$V_{SD}$	$T_J = 25^\circ\text{C}, I_{SD} = 10.0A, V_{GS} = 0V$	--	--	1.4	V
Reverse Recovery Time	$t_{rr}$	$V_R = 400V, I_F = 10.0A,$ $di_F/dt = 100A/\mu\text{s}$	--	500	--	ns
Reverse Recovery Charge	$Q_{rr}$		--	3.2	--	$\mu\text{C}$

### Notes

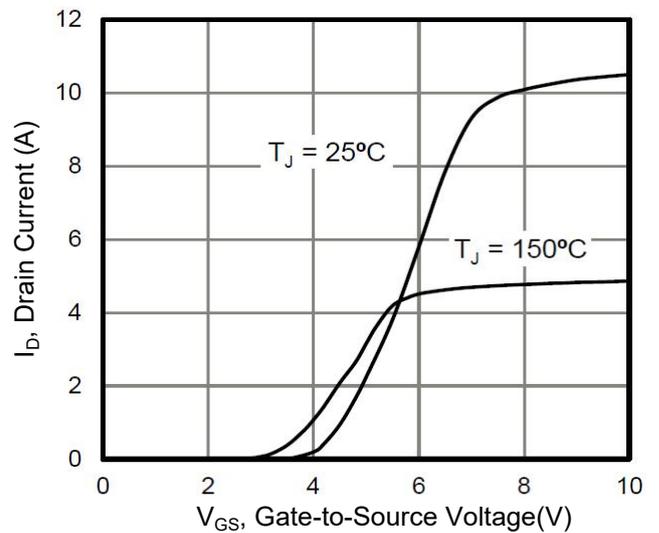
1. Repetitive Rating: Pulse width limited by maximum junction temperature
2.  $I_{AS} = 8A, V_{DD} = 50V, R_G = 25\Omega, \text{Starting } T_J = 25^\circ\text{C}$
3. Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 1\%$
4. Essentially independent of operating temperature

Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

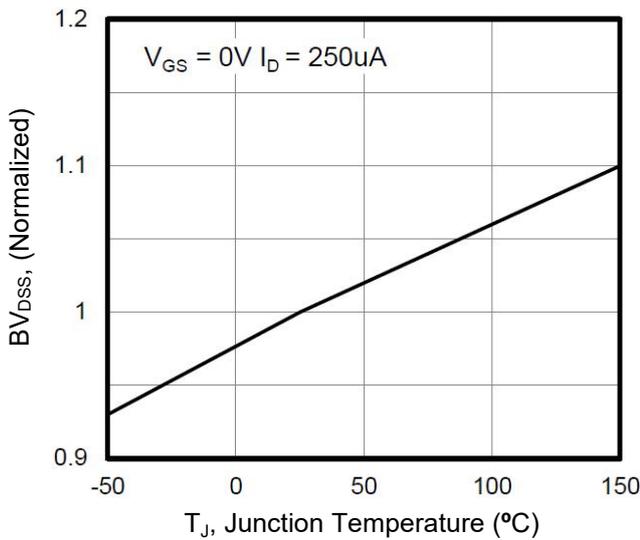
**Figure 1. Output Characteristics**



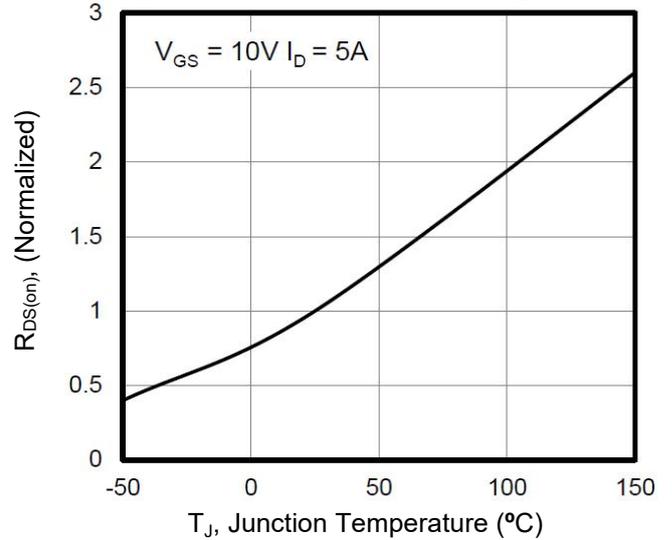
**Figure 2. Transfer Characteristics**



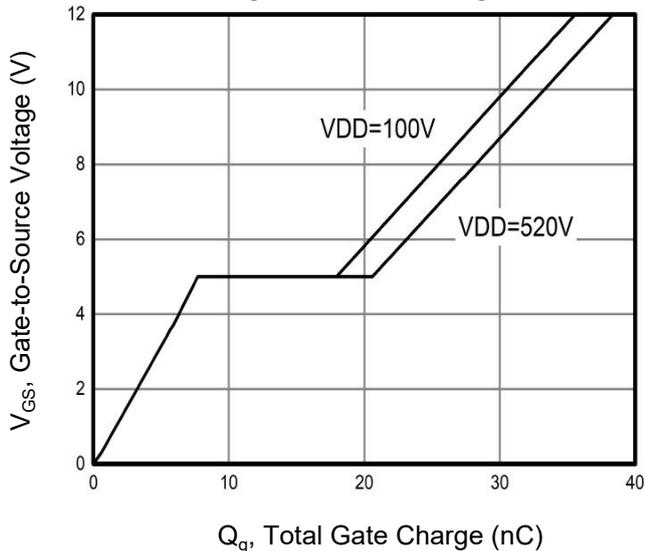
**Figure 3.  $BV_{DSS}$  vs. Temperature**



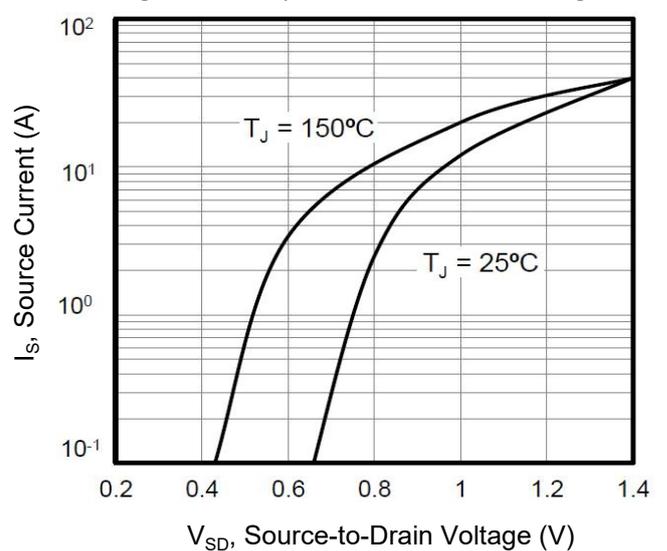
**Figure 4. On-Resistance vs. Temperature**



**Figure 5. Gate Charge**



**Figure 6. Body Diode Forward Voltage**



Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Figure 7. Transient Thermal Impedance  
(TO-220F)

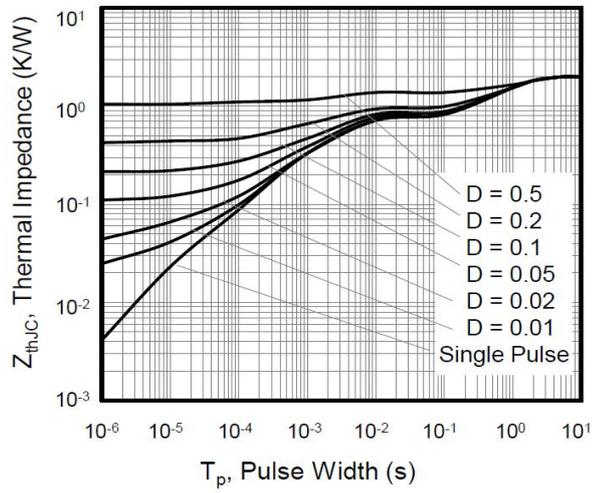
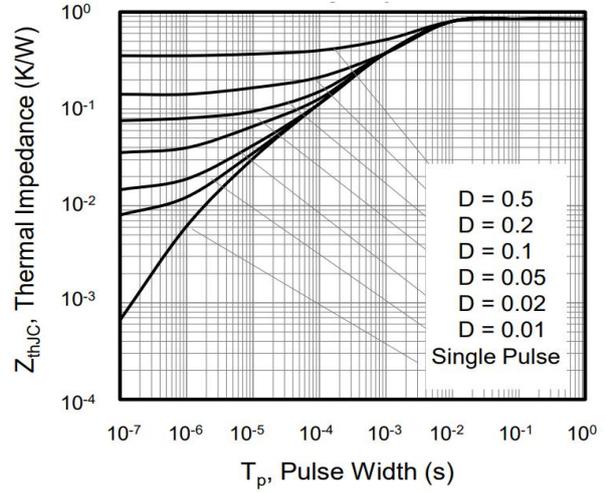
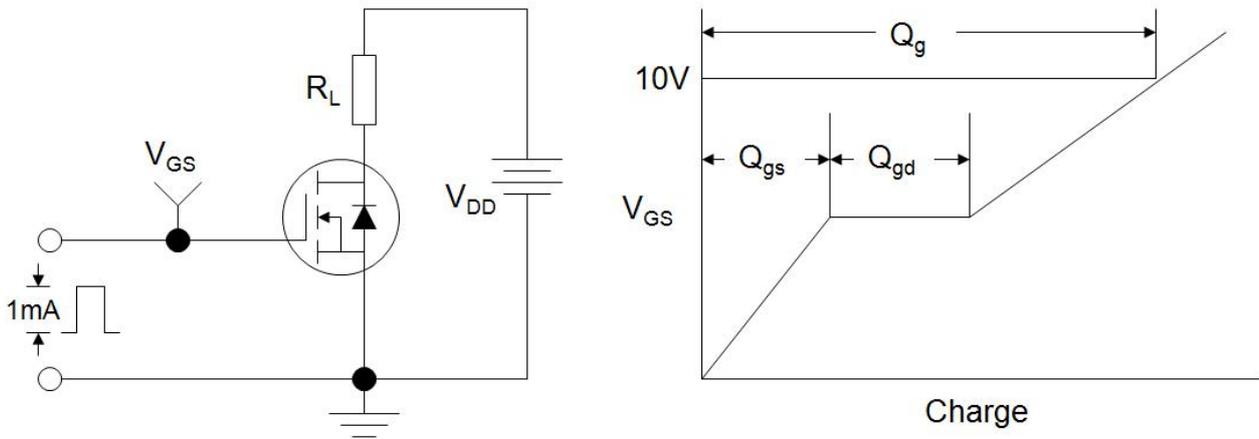


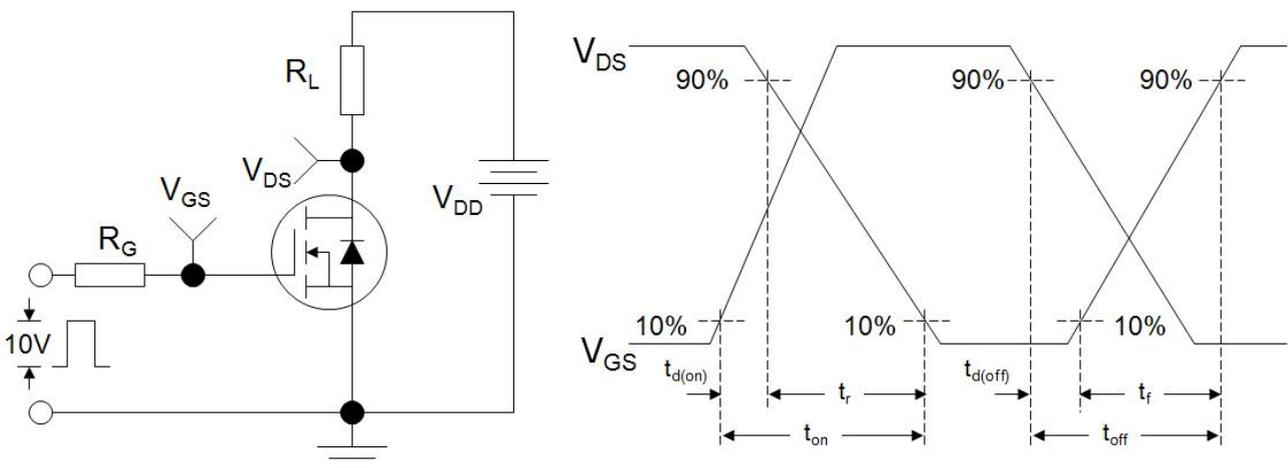
Figure 8. Transient Thermal Impedance  
(TO-262 TO-220 TO-263)



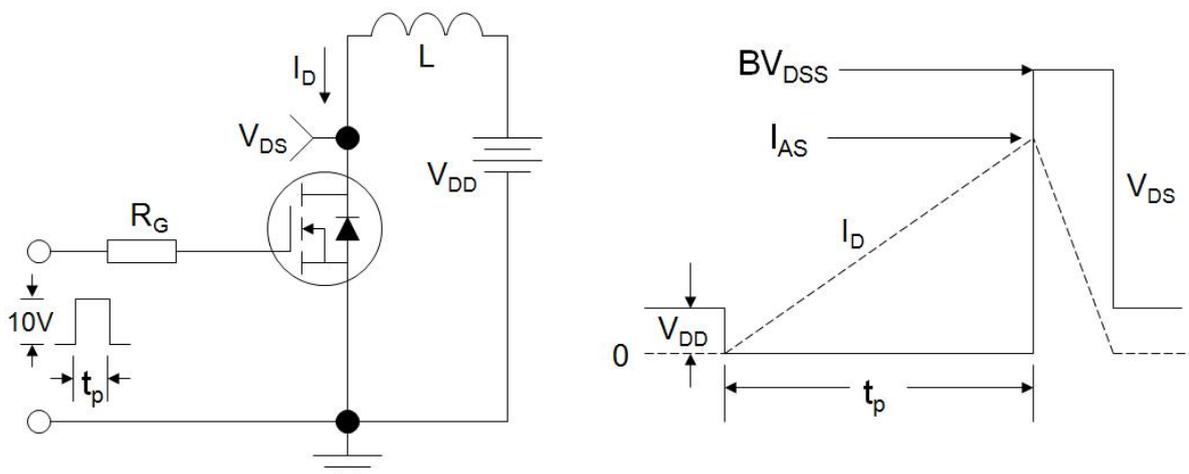
**Figure A: Gate Charge Test Circuit and Waveform**



**Figure B: Resistive Switching Test Circuit and Waveform**



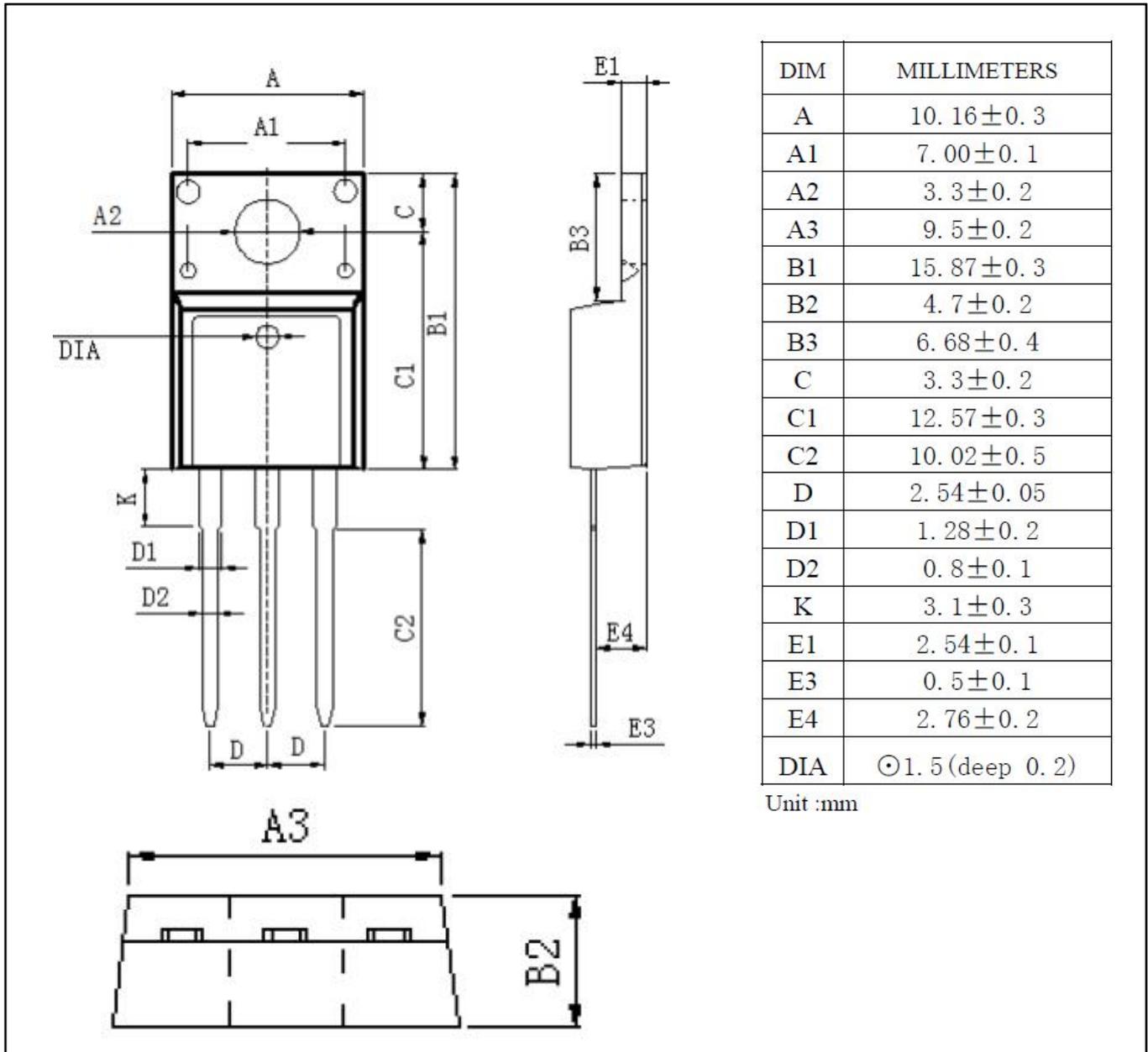
**Figure C: Unclamped Inductive Switching Test Circuit and Waveform**



**Outline Dimension**

Unit: mm

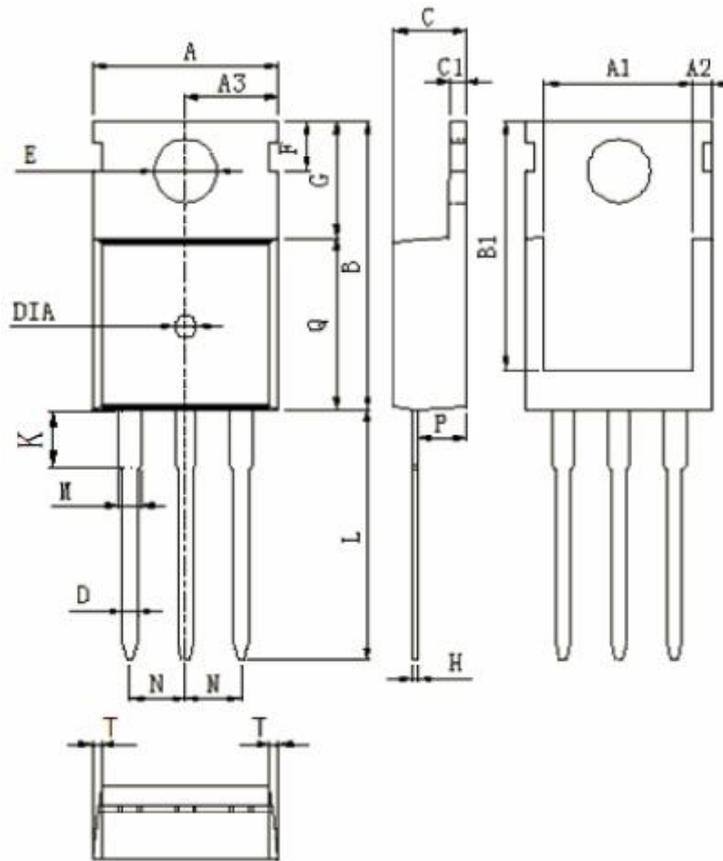
**TO-220F**



Outline Dimension

Unit: mm

TO-220



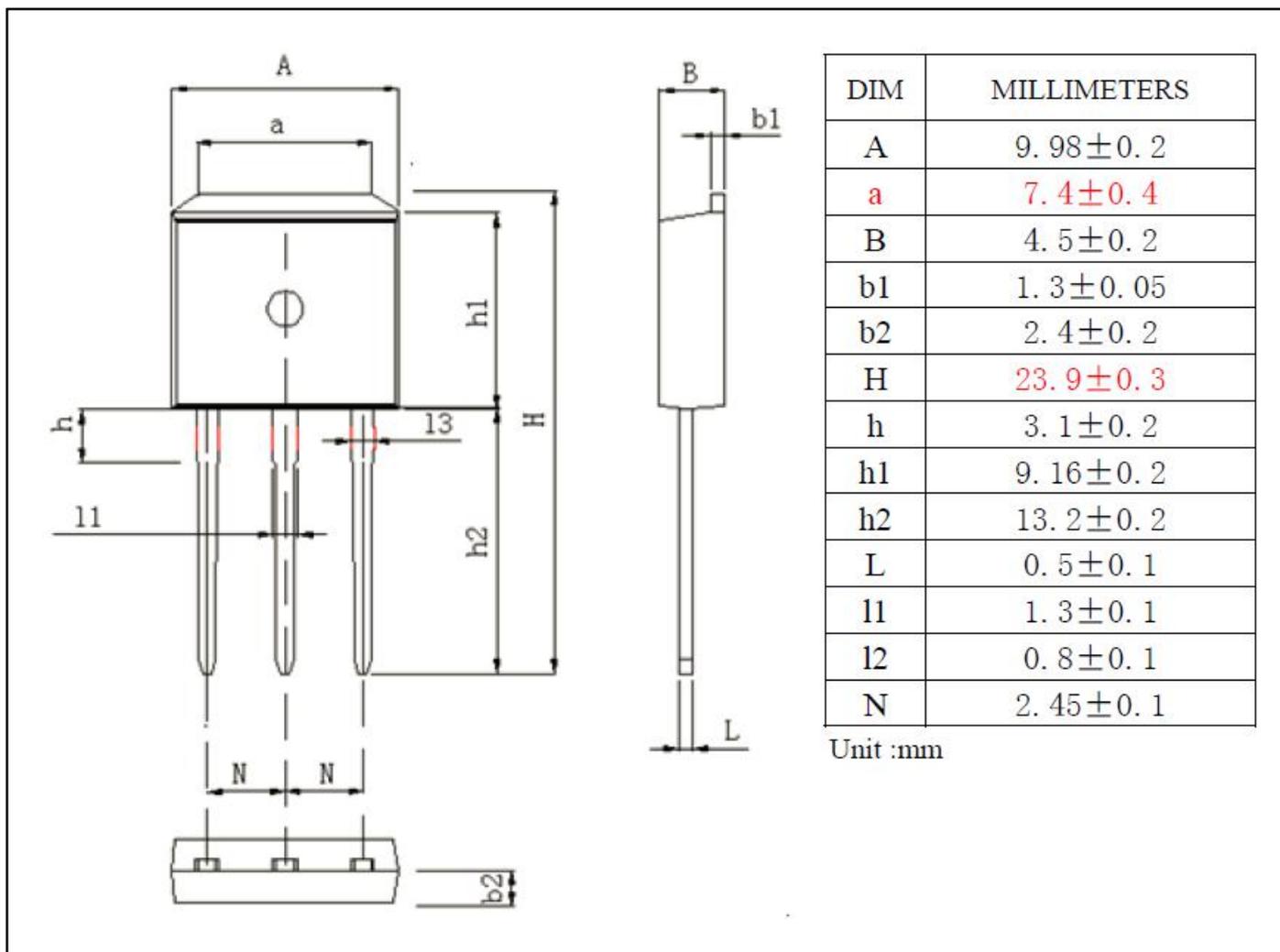
DIM	MILLIMETERS
A	10.0±0.3
A1	8.64±0.2
A2	1.15±0.1
A3	5.0±0.2
B	15.8±0.4
B1	13.2±0.3
C	4.56±0.1
C1	1.3±0.2
D	0.8±0.2
E	3.6±0.2
F	2.95±0.3
G	6.5±0.3
H	0.5±0.1
K	3.1±0.2
L	13.2±0.4
M	1.25±0.1
N	2.54±0.1
P	2.4±0.3
Q	9.0±0.3
T	W:0.35
DIA	⊙1.5(deep 0.2)

Unit :mm

**Outline Dimension**

Unit: mm

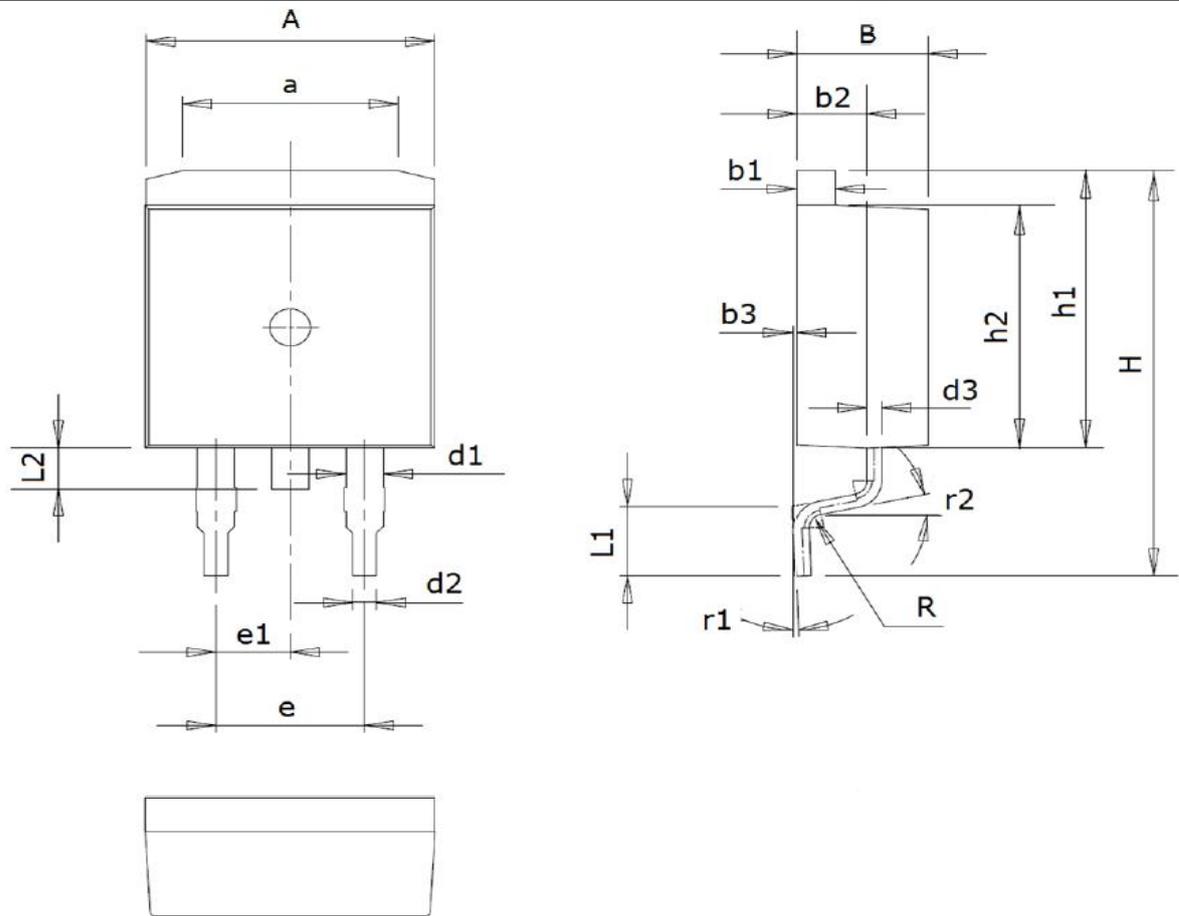
**TO-262**



Outline Dimension

Unit: mm

TO-263



Symbol	Dimensions (mm)	Symbol	Dimensions (mm)	Symbol	Dimensions (mm)
A	9.6~10.0	d2	0.7~0.9	L1	2.4~2.9
a	7.0~7.8	d3	0.4~0.6	L2	1.3~1.8
B	4.3~4.7	e	5.08 (typ)	R	0.5(typ)
b1	1.25~1.35	e1	2.54 (typ)	r1	0~8°
b2	2.2~2.6	H	15.2~15.8	r2	12° (typ)
b3	0~0.2	h1	10.3~10.7		
d1	1.2~1.4	h2	9.1~9.4		